

规格书编号

**SPEC NO :**

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: **SAW FILTER**

MODEL NO 型号: **HDBF19900A22**

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

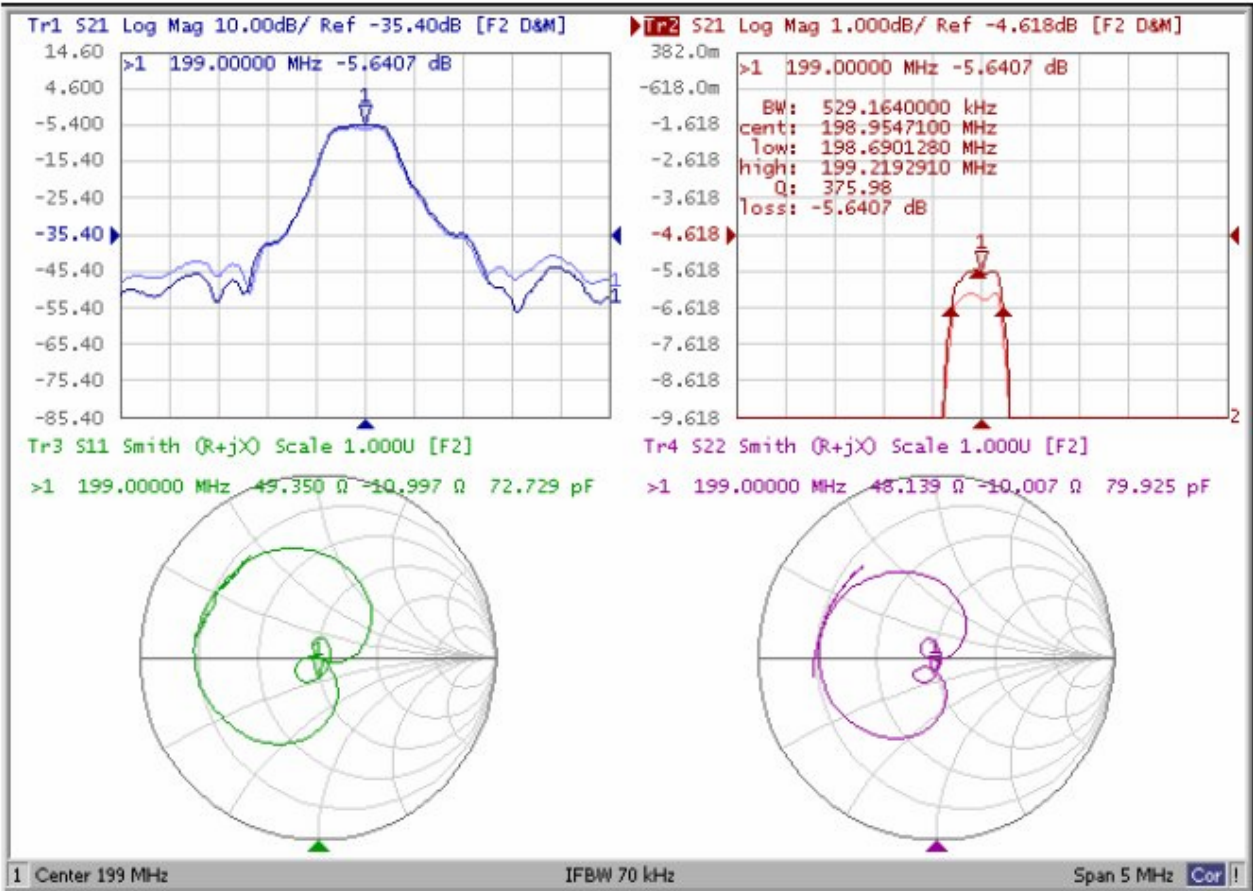
This specification shall cover the characteristics of SAW filter with HDBF19900A22 used for the page system.

## 2. ELECTRICAL SPECIFICATION

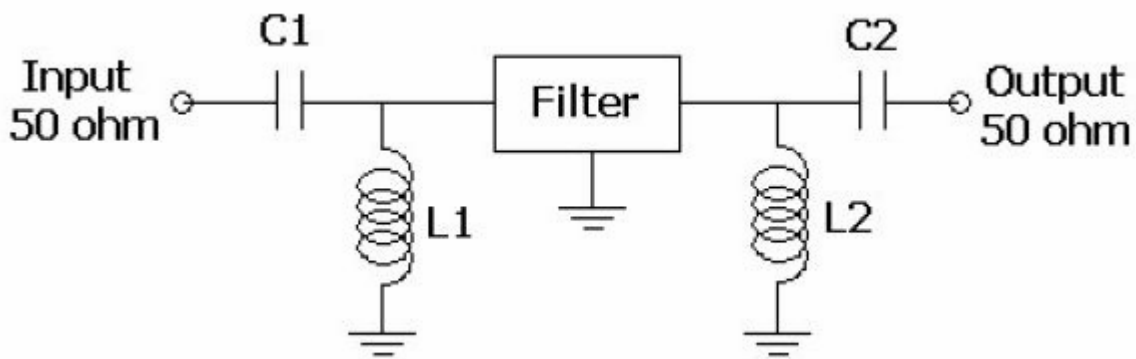
Maximum incident power in passband	+15dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-10°C to +85°C
Suitable for lead-free soldering-Max.soldering profile	260°C for 30s

### Electronic Characteristics

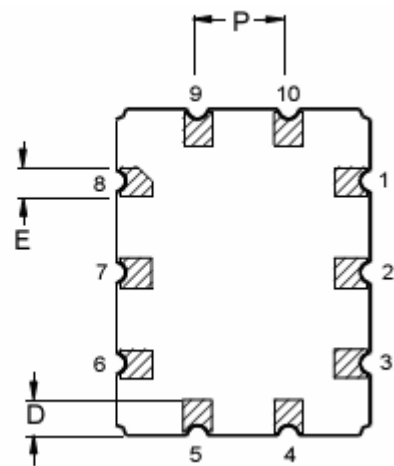
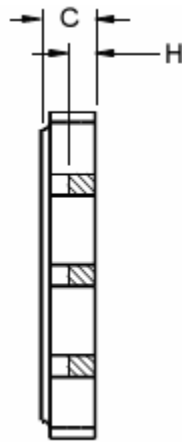
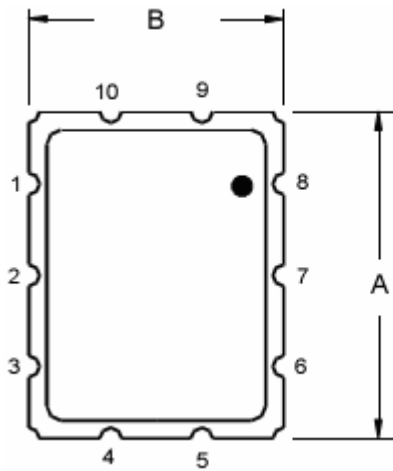
Parameter	Minimum	Typical	Maximum	Unit
Center Frequency	-	199.0	-	MHz
Insertion Loss	-	-	7	dB
1dB Bandwidth	$\pm 100$	-	-	KHz
Amplitude Ripple over $f_0 \pm 100\text{KHz}$	-	-	0.5	dB
$f_0-800$ to $f_0-600\text{KHz}$ and $f_0+600$ to $f_0+800\text{KHz}$	20	-	-	dB
$f_0-30\text{MHz}$ to $f_0-800\text{KHz}$	28	-	-	dB
$f_0+800\text{KHz}$ to $f_0+17\text{MHz}$	28	-	-	dB
$f_0-80\text{MHz}$ to $f_0-30\text{MHz}$	35	-	-	dB
$f_0+17\text{MHz}$ to $f_0+80\text{MHz}$	35	-	-	dB
Group Delay Variation over $f_0 \pm 100\text{KHz}$	-	-	500	nsec
Frequency Temperature coefficient	0.032			ppm/° C



**TEST CIRCUIT**



**4.DIMENSION**



Dimension	mm		
	min	typ	max
A	8.9	9.1	9.3
B	6.9	7.1	7.3
C			1.5
D		0.9	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
2	Input
7	Output
Other	Ground

## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.